YANTAI KESHENG ELECTRONIC CO.,LTD.

APPROVAL SHEET

DATE: June 4, 2012

CUSTOMER:

PRODUCTION NAME: Tuning Fork CRYSTAL UNIT

PART NUMBER: PMX315 32.768KHZ +/-20PPM 12.5PF

PREPARED BY: _____ CONFIRMED BY:____

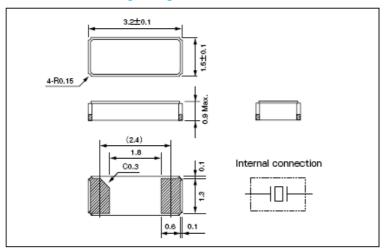
1.ELECTRICAL SPECIFICATIONS

1.1 Hold Type: PMX-315

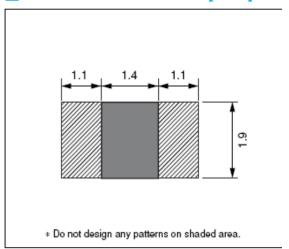
Parameter	Symb	Value	Condition		
Frequency Range	F ₀	32.768Khz			
Frequency Tolerance	f/fo	±20PPM	REF TO 25		
Temperature Coefficient	f/fo	$-0.034 \pm 0.006 \text{ ppm/(})^2$			
Turnover temperature	Tm	25 ± 5			
Operating Temperature Range	T _{OPR}	-40 to 85			
Storage Temperature Range	T _{STG}	-55 to 125			
Quality factor		60,000TYP			
Series resistance	R ₁	60 K	REF TO 25		
Shunt Capacitance	Co	1.8PF TYP	0.9~2.0PF		
Motional Capacitance	C ₁	0.0030TYP			
Load Capacitance	C _L	12.5PF			
Insulator Resistance	IR	500 M	DC100V ± 15V		
Drive Level	DL	1 W			
Capacitance ratio	r	450TYP			
Aging	f/fo	±5PPM	at 25 ± 3		

1.2 DIMENSION Unit:mm

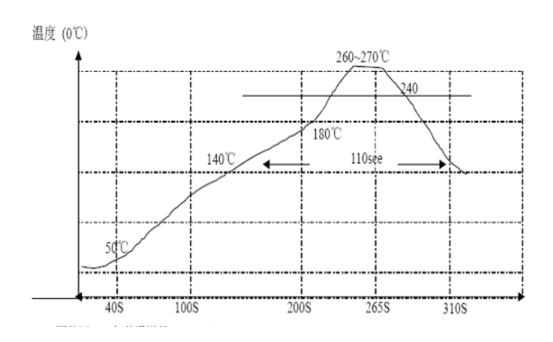
DIMENSION [mm]



■SOLDER PAD LAYOUT [mm]



1.3 Reflow solder



2. TEST STANDARD

2.1 GENERAL ELECTRICAL CHARACTERISTICS AND VISUAL TESTING

- 2.1.1 LOT CLASSIFICATION: If the quantity is 1,000 pcs or more, 1,000 pcs is one lot.
- 2.1.2 SAMPLING TEST METHOD: MIL-STD-105E G-II
- 2.1.3 TEST LEVEL
 - A] HIGH LEVEL DEFECT: AQL 0.065% [200 PCS]
 - B] MEDIUM LEVEL DEFECT: AQL 0.25% [50 PCS]
 - C] LOW LEVEL DEFECT: AQL 0.4% [32 PCS]
- 2.1.4 DEFECT CLASSIFICATION
 - A] HIGH LEVEL
 - **@NO FREQUENCY**
 - @MIXING
 - **@LEAK DEFECT**
 - B] MEDIUM LEVEL ELECTRICAL CHARACTERISTIC DEFECT
 - @FREQUENCY
 - @OSCILLATION
 - **@ELECTRICAL CURRENT**
 - **@OTHER ELECTRICAL CHARACTERISTICS DEFECT**
 - C] VISUAL
 - @MARKING
 - @WELDING
 - @LEADS
 - **@OTHER VISUAL DEFECT**

TESTING METHOD AND ITS STANDARD CAN BE MODIFIED DEPENDING ON THE CUSTOMER'S REQUEST.

2.2 EQUIVALENT CIRCUITS Symbol for crystal unit c₀ **-**|

3. RELIABILITY TEST STANDARD

3.1 ENVIRONMENTAL

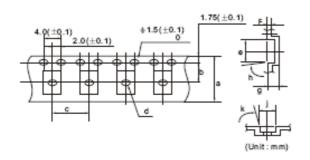
TEST ITEM	TESTING PROCEDURE & CONDITIONS	EVALUATION
1. THERMAL SHOCK TEST	1. The test should be performed in accordance with the following condition for 10 cycle. +85°C -40°C 30min. 1 cycle 2. The crystal unit should be kept in room temperature for 1 hour then tested.	The crystal unit should fulfill the specified requirements of the electrical characteristics and appearance.
2. HUMIDITY	1.temperature: +40℃±2℃ RELATIVE HUMIDITY: 90~95% TEST PERIOD: 48 HOURS 2. The crystal unit should be kept in room temperature for 1 hour then tested.	The crystal unit should fulfill the specified requirements of the electrical characteristics and appearance.
3. COLD TEMPERATURE TEST	 TEMPERATURE: -40℃±2℃ TEST PERIOD: 2 HOURS The crystal unit should be kept in room temperature for 1 hour then tested. 	The crystal unit should fulfill the specified requirements of the electrical characteristics and appearance.
4. THERMAL TEST	 TEMPERATURE: +85℃±2℃ TEST PERIOD: 24 HOURS The crystal unit should be kept in room temperature for 1 hour then tested. 	The crystal unit should fulfill the specified requirements of the electrical characteristics and appearance.
5. RAPID CHANGE IN TEMPERATURE	1. TEMPERATURE: +85℃±2℃ TEST PERIOD: 120 HOURS 2. The crystal unit should be kept in room temperature for 1 hour then tested.	The crystal unit should fulfill the specified requirements of the electrical characteristics and appearance.

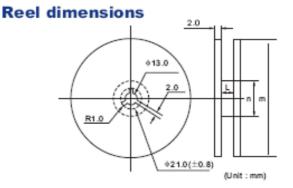
3.2 MECHANICAL

TEST ITEM	TESTING PROCEDURE & CONDITIONS	EVALUATION		
1.LEAD TENSILITY	 FIX THE UNIT. APPLY 2LB OF WEIGHT AXIS TO THE LEADS. TIME: 5 SECONDS 	SHOULD PASS SEALING AND VISUAL TEST		
2. LEAD BENDING	 ATTACH 1 LB OF WEIGHT TO EACH OF THE LEADS. BENDING ANGLE: 90° (FROM THE NORMAL POSITION TO 45° OPPOSITE DIRECTION) BENDING TIME: 3 SECONDS(EACH DIRECTION) NUMBER OF BENDING: 2 TIMES 	SHOULD PASS SEALING AND VISUAL TEST		
3. LEADS SOLDERABILITY	 DIP THE LEADS INTO FLUX(ROJIN METHANOL) FOR 5 SECONDS DIP THE LEADS INTO 250±5℃ 99% Sn DIPPING SOLUTION FOR 5 SECONDS. 	THE DIPPED PART OF THE LEADS SHOULD HAVE 90~95% Sn COATING.		
4. SOLDERING HEAT RESISTANCE TEST	1. PERFORM ELECTRICAL CHARACTERISTICS TEST BEFORE STARTING THIS PROCEDURE. 2. DIP THE LEADS INTO FLUX(ROJIN METHANOL) FOR 5 SECONDS. 3. DIP THE LEADS INTO 260±5℃ 99% Sn DIPPING SOLUTION FOR 5 SECONDS. 4. TAKE THE UNIT OUT, STORE AT ROOM TEMPERATURE FOR 30 SECONDS THEN MEASURE THE ELCTRICAL CHARACTERISTICS.	SHOULD PASS SEALING AND VISUAL TEST		
5. VIBRATION	1. PERFORM ELECTRICAL CHARACTERISTICS TEST BEFORE STARTING THIS PROCEDURE. 2. THE UNIT SHOULD BE FIXED ONTO A VIBRATING MACHINE AND THEN SHAKEN X.Y.Z DIRECTIONS. VIBRATING FREQUENCY: 10 ~ 55 Hz AMPLITUDE: 0.03 Inch FACTOR TIME: 1 MINUTES TESTING TIME: 30 MINUTES EACH FOR X, Y, Z DIRECTIONS	SHOULD PASS SEALING AND VISUAL TEST		
6. DROP TEST	PERFORM ELECTRICAL CHARACTERISTICS TEST BEFORE STARTING THIS PROCEDURE. FROM THE HEIGHT OF 500mm DROP THE UNIT 3 TIMES ONTO A HARD RUBBER SURFACE.	SHOULD PASS SEALING AND VISUAL TEST		
7. LEAK TEST	USE Helium Leak Detector. Bombing PRESSURE : 5kg/ਯਾਂ Bombing TIME : 2 HOURS LEAK SHOULD BE LESS THAN 1E-8 atm.cc/sec.	GAS OR AIR SHOULD NOT BE DETECTED.		
8. MARKING ERASE	SUBMERGE THE UNIT INTO IPA[ISOPROPYL ALCOHOL] SOLUTION FOR 10 MINUTES AND BRUSH THE MARKING 10 TIMES WITH A TOOTH BRUSH.	MARKING SHOULD NOT BE ERASED.		

4. Packing

Taping dimensions





Model Region	Quantity (pcs / reel)	а	b	С	d (Φ)	ө	f	h (Max.)	j	k (Max.)	L	m (Φ)	n (Φ)
PSX-415	3,000	12.0	5.5	4.0	1.0	4.5	1.0	5°	1.9	5°	13.0	180	60

- 4.2 PACKAGING METHOD
- 4.2.1 TAPE & REEL AS SHOWN IN ABOVE DIMENSION,
- 4.2.2 INSERT 3,000 PCS OF TAPE & REEL COVERED WITH SHOCK ABSORBANT PAD INTO THE INNER BOX(INNER BOX SHOULD HAVE DESCRIPTION OF THE PART CONTAINED) AS SHOWN IN PICTURE1.

INNER-BOX CAN ACCOMODATE UPTO 3,000PCS.[PICTURE2]

- 4.2.3 INSERT SHOCK-ABSORBANT PAD ON ALL SIDES(INCLUDING TOP), AND THEN INSERT UPTO 5 INNER BOXES INTO THE OUTER BOX. [PICTURE3]
- 4.2.4 ON THE INNER-BOX COVER, LABEL CONTENTS OF THE BOX(FREQUENCY, LOAD CAPACITANCE, AND QUANTITY).
- 4.2.5 TO PREVENT INNER-BOX COVER OPENING DUE TO SHOCK, FASTEN THE COVER WITH A CLEAR TAPE AS SHOWN IN PICTURE4.









TURE1 PICTURE2

PICTURE3

PICTURE4

5. CAUTION

* IN ORDER TO MAINTAIN QUALITY, WITHOUT CHANGE IN CHARACTERISTICS OF THE CRYSTAL UNITS, PLEASE FOLLOW BELOW RECOMMENDATION.

5.1 SHOCK

5.1.1 ALL CRYSTAL UNITS HAVE A THIN CRYSTAL BLANKS WITHIN, IF IT IS DROPPED ABOVE THE RECOMMENDED DROPPING HEIGHT (500mm), THE SPECIFIC CHARACTERISTICS AND APPEARANCE CAN BE CHANGED. PLEASE PAY SPECIAL ATTENTION TO EXTERNAL SHOCK.

5.2. ENVIRONMENTAL

- 5.2.1 CRYSTAL UNITS' FREQUENCY CAN BE CHANGED DUE TO SURROUNDING TEMPERATURE, IF IT IS STORED NEXT TO A HIGH TEMPERATURE HEATER (ABOVE+85°C) OR BELOW 40°C, AND A STRONG LIGHT SOURCE FOR LONG PERIOD OF TIME, THE ELECTRICAL CHARACTERISTICS CAN BE CHANGED. IT IS SUGGESTED THAT THESE ENVIROMENTS BE AVOIDED.
- 5.2.2 IF THE UNIT IS PLACED IN A HUMID ENVIRONMENT, LEAD TERMINAL CAN BE DAMAGED; THEREFORE, DO NOT STORE THE CRYSTAL UNITS IN A HUMID ENVIRONMENT.
- 5.2.3 CRYSTAL UNIT HAS VIBRATING CHARACTERISTICS. IF IT IS PLACED WHERE VIBRATION EXISTS, THE OPERATING CHARACTERISTICS CAN BE ALTERED; THEREFORE, THIS ENVIRONMENT SHOULD BE AVOIDED.

5.3 LEADS

- 5.3.1 IF THE LEADS ARE BENT 90° FROM ITS AXIS FOR MORE THAN 2 TIMES THE TERMINAL COULD BE DISCONNECTED; THEREFORE, DO NOT BENT THE LEADS EXCESSIVELY.
- 5.3.2 AFTER SOLDERING CRYSTAL UNITS INTO A PCB, IMPACTING THE UNIT FROM THE TOP, BOTTOM, LEFT OR RIGHT SIDE OF THE UNIT CAN SHATTER THE GLASS PORTION OF THE BASE, RENDERING THE UNIT USELESS.

5.4 ASSEMBLY METHOD

- 5.4.1 CORRECT ULTRASONIC FREQUENCY FOR CLEANING SHOULD BE LESS THAN 20KHz.
- 5.4.2 SOLDERING SHOULD BE DONE USING IEC 61760-1 OR Pb-Free Products.

5.5 STORAGE

5.5.1 IF THE CRYSTAL UNITS ARE STORED IN HUMID OR SALTY ENVIRONMENT, APPEARANCE CAN BE CHANGED AND SOLDERABILITY CAN DETERIORATE; THEREFORE, AVOID STORING IN SUCH ENVIRONMENT. DO NOT STORE THE CRYSTAL UNIT MORE THAN 3 MONTHS.

6. Pb-Free PRODUCTS

Joinic Pb-free program.

The Joinic Pb-free program is implemented in accordance with European Union (EU) Legislation titled "Restriction of the use of certain Hazardous Substances (RoHS)" including banning the use of Pb in electronic assemblies after July 1, 2006.

Joinic Definitions

Pb-Free Classification: Component and Assembly Pb content shall be less than 0.1% by weight of the device (in accordance to IPC/EIA J-STD-006) and shall not be intentionally introduced.

Components: Joinic's definition of components apply to quartz crystal devices

Assemblies: Joinic's definition of assemblies apply to oscillator devices (XO, VCXO and TCXO's)

Recommended Solder Composition

Joinic's is following industry trend of using alloy range Sn-Ag(3.4-4.1)-Cu(0.45-0.9) for reflow and wave soldering.

Pb-free Part Number Identification:

When applicable, the Joinic specification sheet shall indicate if the device is classified as Pb-free.

Marking and Labeling: Joinic has a Pb-free labeling method for the packaging of all Pb-free products. The lowest level shipping container shall identify the products as Pb-free.